LA B6SP

Power SIDELED®

Power SIDELED features a compact package with a wide brightness range and high luminous efficiency.

Applications

- Cluster, Button Backlighting
- Signalling

Features:

- Package: white PLCC-2 package, clear silicone resin
- Chip technology: Thinfilm
- Typ. Radiation: 120° (Lambertian emitter)
- Color: λ_{dom} = 617 nm (● amber)
- Corrosion Robustness Class: 3B
- Qualifications: AEC-Q102 Qualified
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)

Ordering Information

Type	Luminous Intensity [1] I_F = 140 mA I_v	Ordering Code
LA B6SP-DBFA-24-G3R3	5.6 ... 14.0 cd	Q65112A6208
LA B6SP-EAFB-24-G3R3	7.1 ... 18.0 cd	Q65112A9519

Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T_{op}	min. max.	-40 °C 110 °C
Storage Temperature	T_{stg}	min. max.	-40 °C 110 °C
Junction Temperature	T_j	max.	125 °C
Junction Temperature for short time applications*	T_j	max.	150 °C
Forward current T_S = 25 °C	I_F	min. max.	5 mA 200 mA
Surge Current t ≤ 10 µs; D = 0.005 ; T_S = 25 °C	I_{FS}	max.	1000 mA
Reverse voltage (2) T_S = 25 °C	V_R	max.	12 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}		2 kV

* The median lifetime (L70/B50) for Tj = 150°C is 100h.

Characteristics

I_F = 140 mA; T_S = 25 °C

Parameter	Symbol		Values
Dominant Wavelength [3] I_F = 140 mA	λ_{dom}	min. typ. max.	612 nm 617 nm 624 nm
Spectral Bandwidth at 50% $I_{rel,max}$	$\Delta\lambda$	typ.	18 nm
Viewing angle at 50% I_V	2φ	typ.	120 °
Forward Voltage [4] I_F = 140 mA	V_F	min. typ. max.	1.90 V 2.20 V 2.50 V
Reverse current [2] V_R = 12 V	I_R	typ. max.	0.01 µA 10 µA
Real thermal resistance junction/solderpoint [5]	$R_{thJS\ real}$	typ. max.	40 K / W 50 K / W
Electrical thermal resistance junction/solderpoint [5] with efficiency η_e = 40 %	$R_{thJS\ elec.}$	typ. max.	24 K / W 30 K / W

Brightness Groups

Group	Luminous Intensity [1] I_F = 140 mA min. I_v	Luminous Intensity. [1] I_F = 140 mA max. I_v	Luminous Flux [6] I_F = 140 mA typ. Φ_V
DB	5.6 cd	7.1 cd	19.9 lm
EA	7.1 cd	9.0 cd	25.3 lm
EB	9.0 cd	11.2 cd	31.7 lm
FA	11.2 cd	14.0 cd	39.6 lm
FB	14.0 cd	18.0 cd	50.2 lm

Forward Voltage Groups

Group	Forward Voltage [4] I_F = 140 mA min. V_F	Forward Voltage [4] I_F = 140 mA max. V_F
G3	1.90 V	2.05 V
K3	2.05 V	2.20 V
N3	2.20 V	2.35 V
R3	2.35 V	2.50 V

Wavelength Groups

Group	Dominant Wavelength [3] I_F = 140 mA min. λ_{dom}	Dominant Wavelength [3] I_F = 140 mA max. λ_{dom}
2	612 nm	616 nm
3	616 nm	620 nm
4	620 nm	624 nm

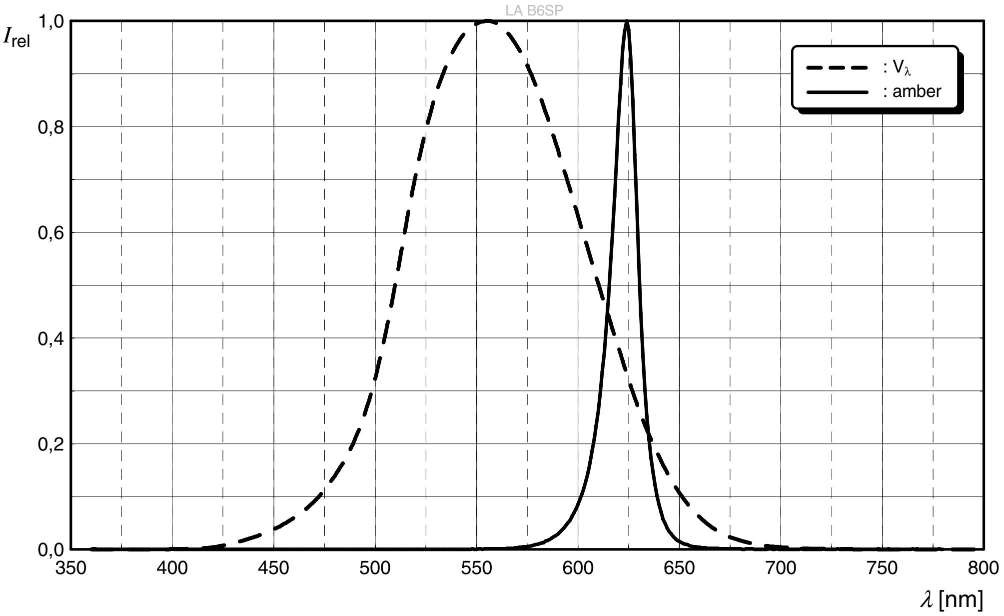
Group Name on Label

Example: DB-2-G3

Brightness	Wavelength	Forward Voltage
DB	2	G3

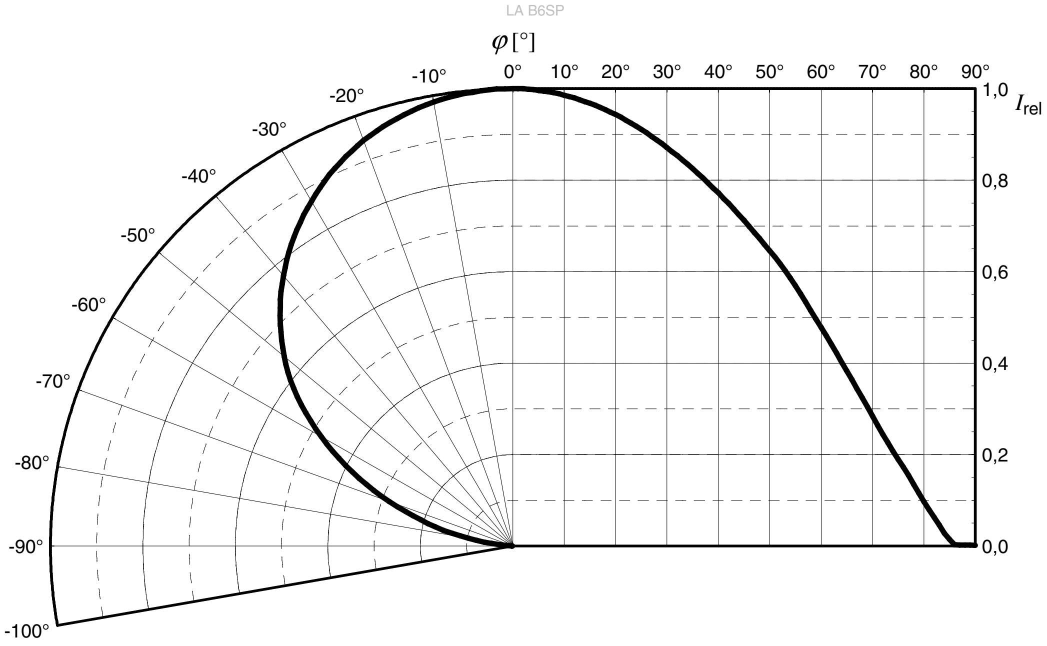
Relative Spectral Emission [6)]

$I_{rel} = f(\lambda)$; $I_F = 140$ mA; $T_S = 25$ °C



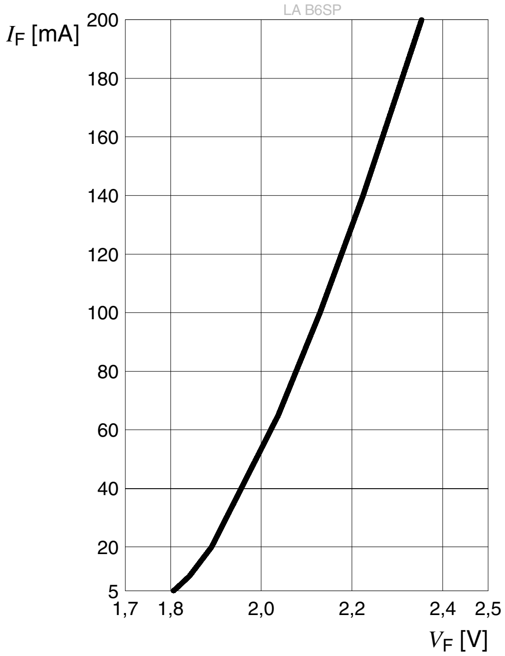
Radiation Characteristics [6)]

$I_{rel} = f(\phi)$; $T_S = 25$ °C



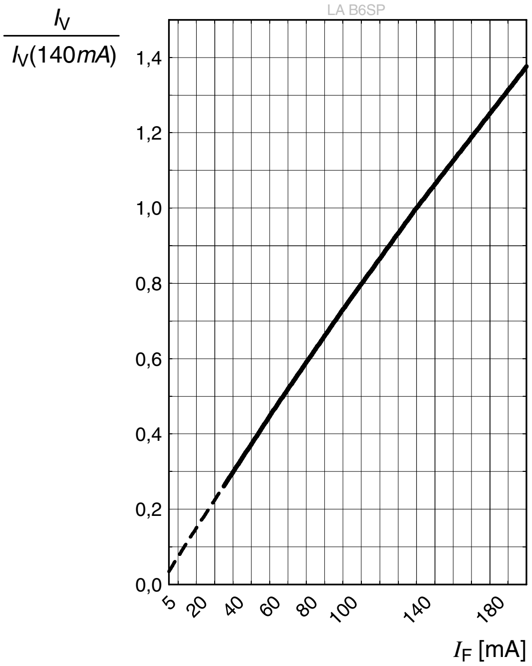
Forward current [6)]

$I_F = f(V_F)$; T_S = 25 °C



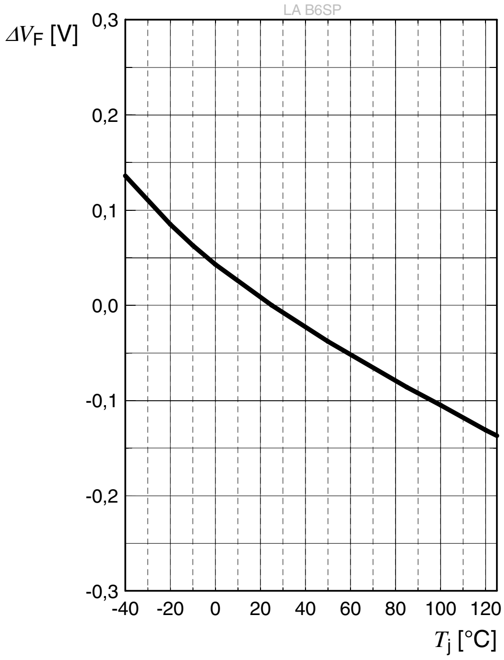
Relative Luminous Intensity [6), 7)]

$I_V/I_V(140\ mA) = f(I_F)$; T_S = 25 °C



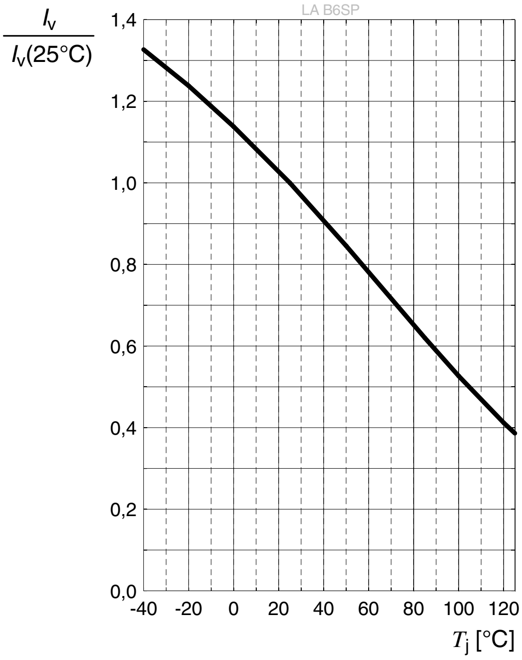
Forward Voltage [6)]

$\Delta V_F = V_F - V_F(25\ °C) = f(T_j);\ I_F = 140\ mA$



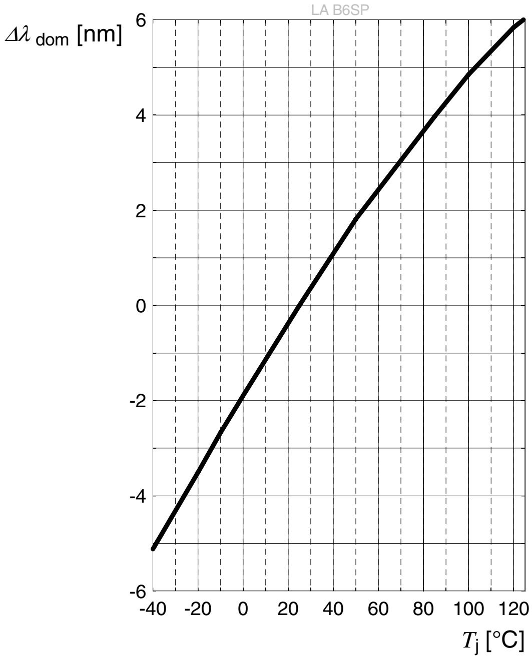
Relative Luminous Intensity [6)]

$I_v/I_v(25\ °C) = f(T_j);\ I_F = 140\ mA$



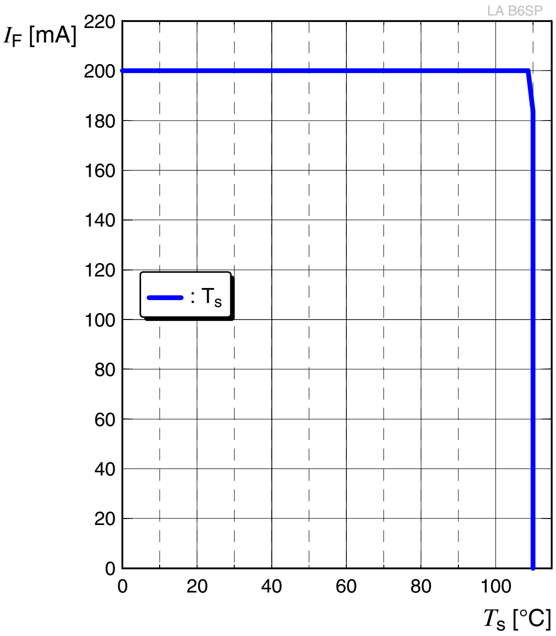
Dominant Wavelength [6)]

$\Delta\lambda_{dom} = \lambda_{dom} - \lambda_{dom}(25\ °C) = f(T_j);\ I_F = 140\ mA$



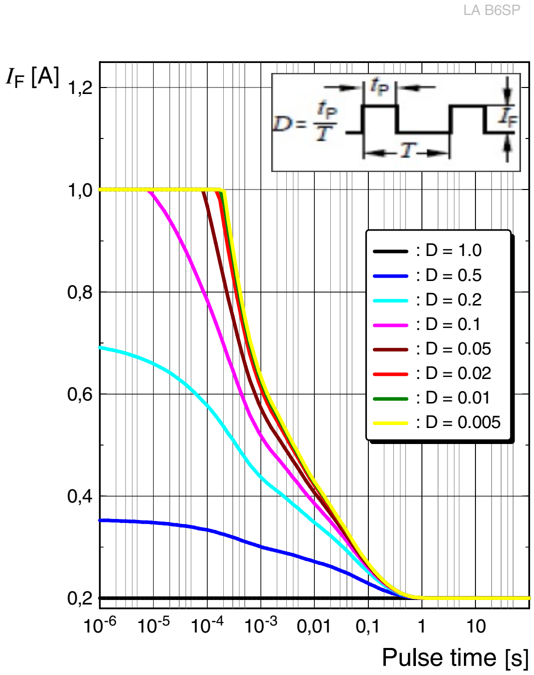
Max. Permissible Forward Current

$I_F = f(T)$



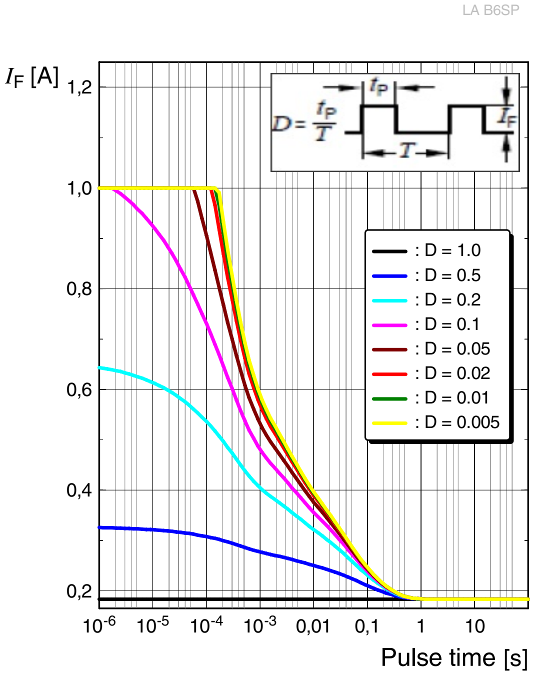
Permissible Pulse Handling Capability

$I_F = f(t_p)$; D: Duty cycle

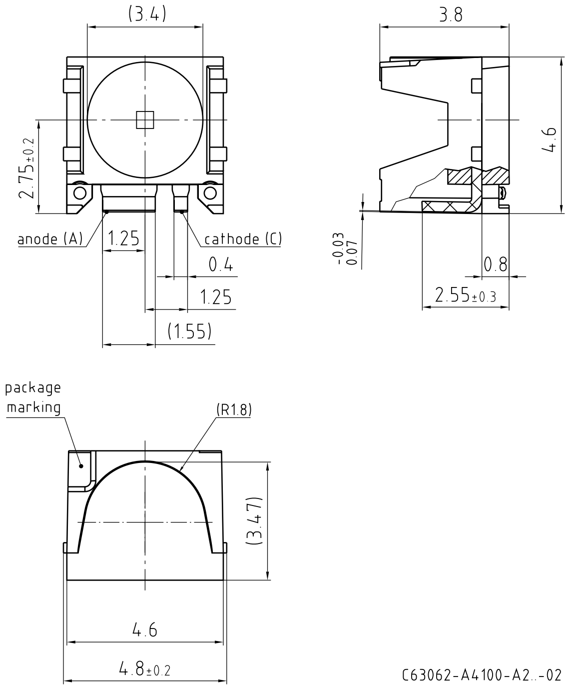


Permissible Pulse Handling Capability

$I_F = f(t_p)$; D: Duty cycle



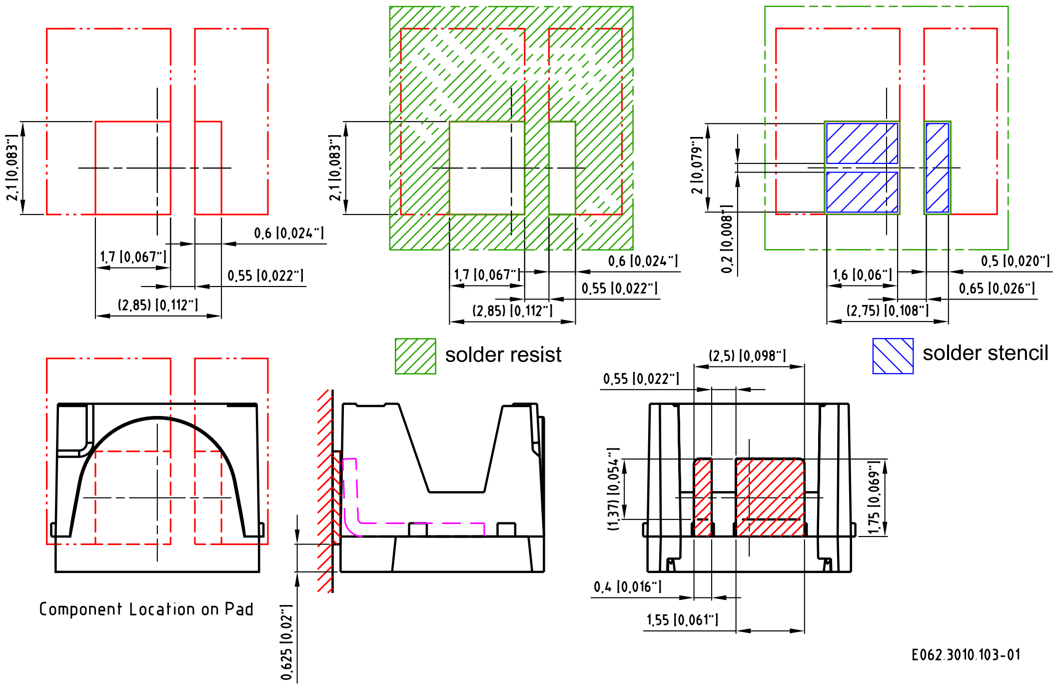
Dimensional Drawing [8]



Further Information:

Approximate Weight:	86.5 mg
Package marking:	Anode
Corrosion test:	Class: 3B Test condition: 40°C / 90 % RH / 15 ppm H_2S / 14 days (stricter than IEC 60068-2-43)

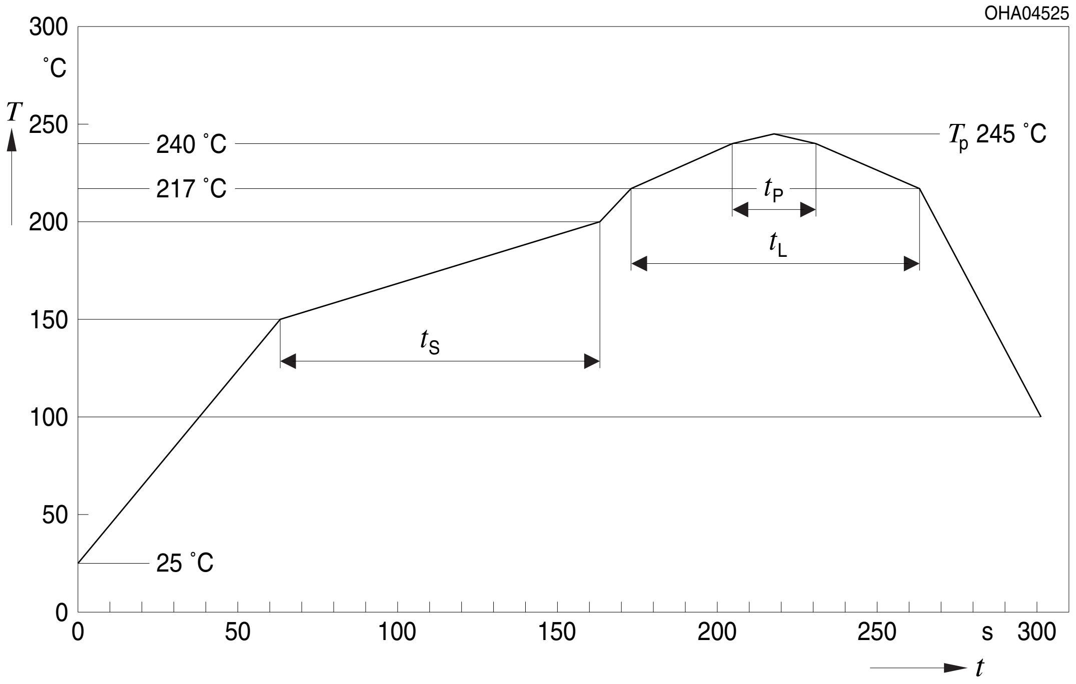
Recommended Solder Pad 8)



For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere.

Reflow Soldering Profile

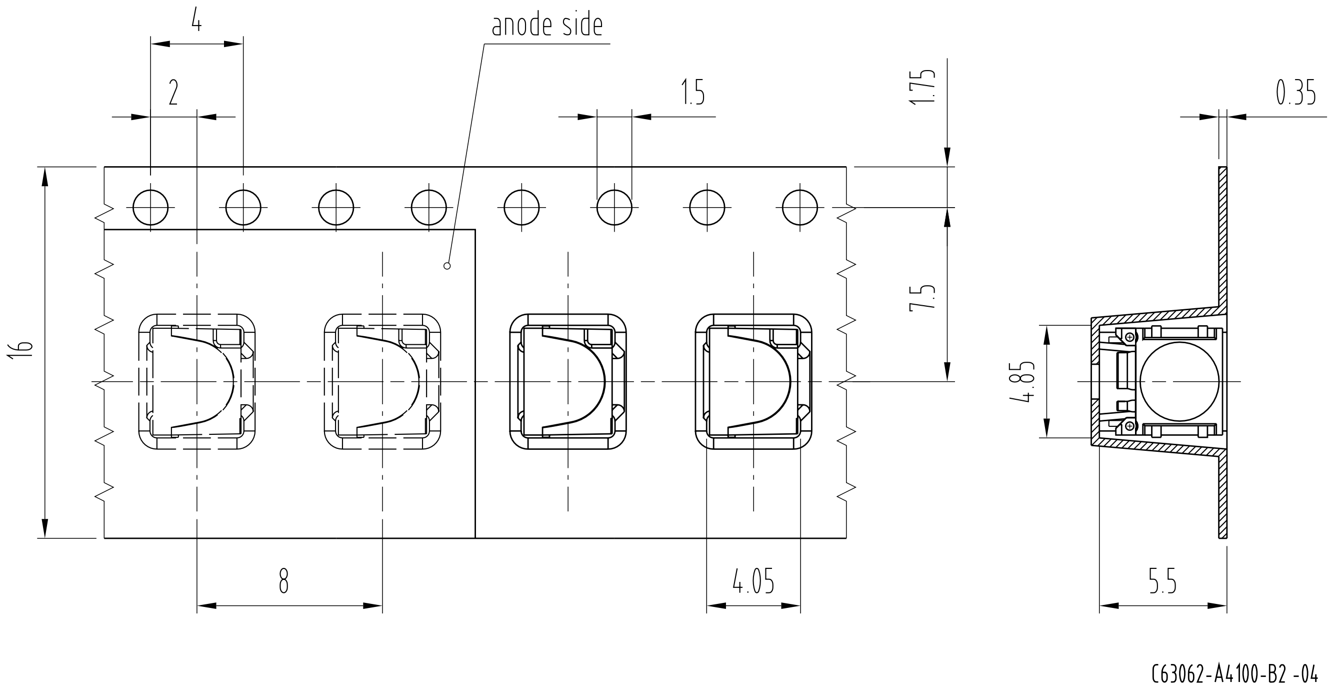
Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



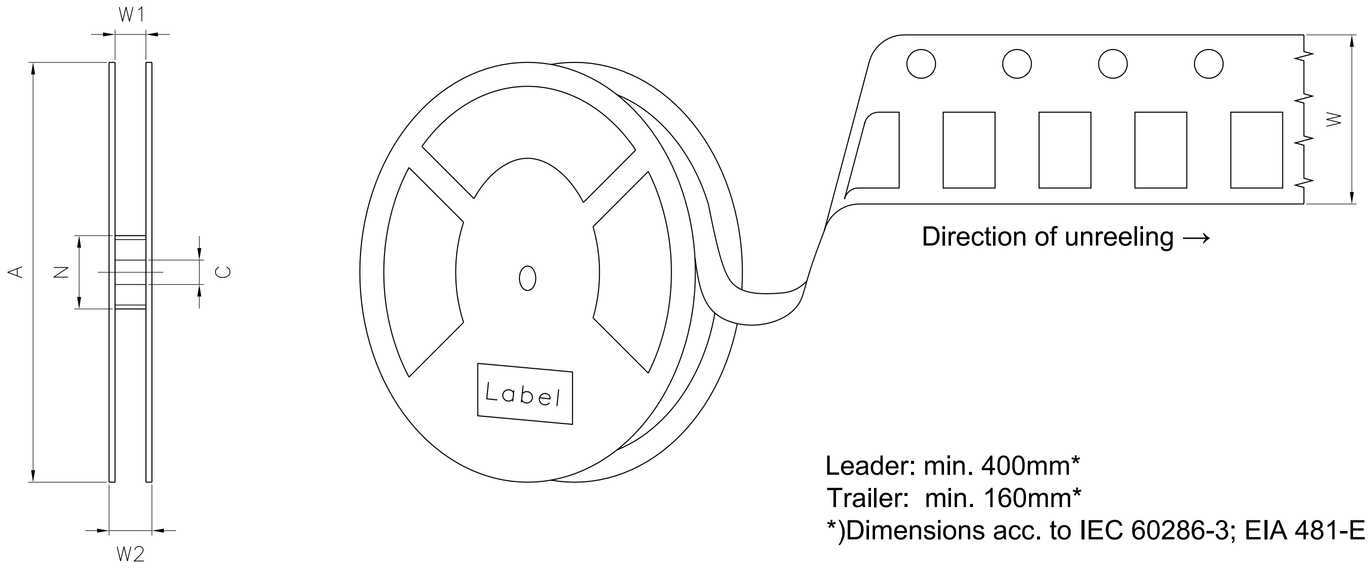
Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_S T_{Smin} to T_{Smax}	t_S	60	100	120	s
Ramp-up rate to peak*) T_{Smax} to T_P			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_P		245	250	°C
Time within 5 °C of the specified peak temperature T_P - 5 K	t_P	10	20	30	s
Ramp-down rate* T_P to 100 °C			3	4	K/s
Time 25 °C to T_P				480	s

All temperatures refer to the center of the package, measured on the top of the component
* slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

Taping [8)]



Tape and Reel [9)]



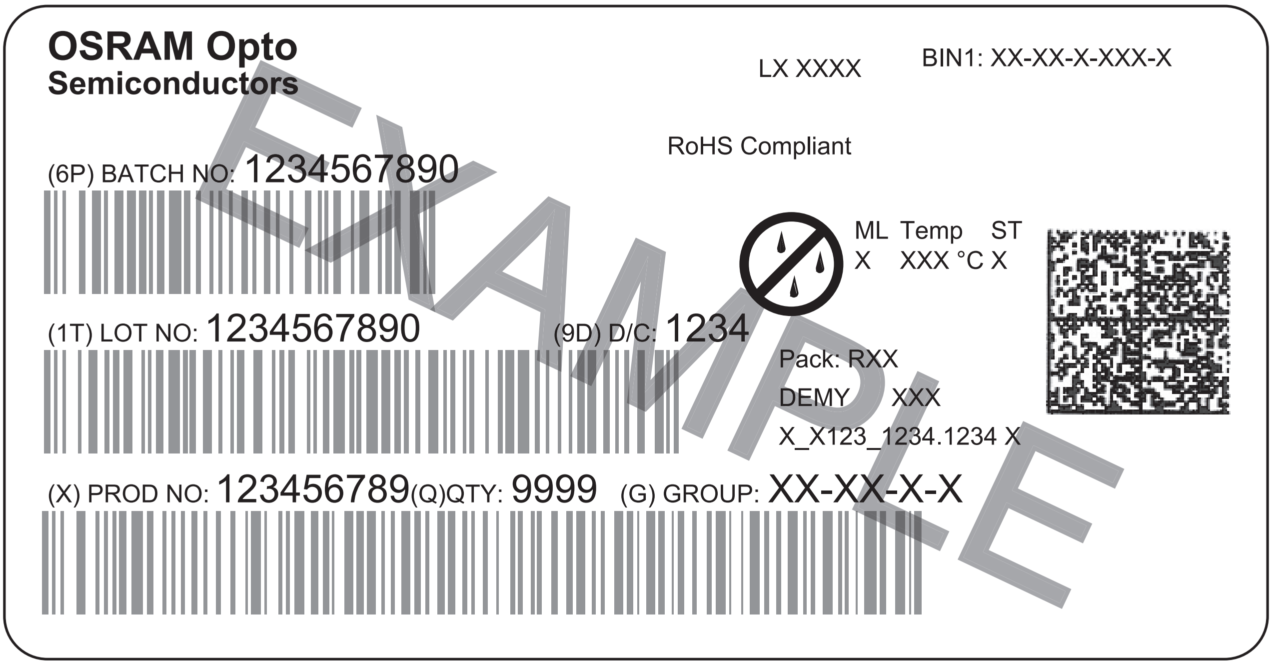
Direction of unreeling →

Leader: min. 400mm*
Trailer: min. 160mm*
*)Dimensions acc. to IEC 60286-3; EIA 481-E

Reel Dimensions

A	W	N_{min}	W_1	$W_{2\,max}$	Pieces per PU
330 mm	16 + 0.3 / - 0.1 mm	60/100 mm	16.4 + 2 mm	22.4 mm	1200

Barcode-Product-Label (BPL)



OSRAM Opto
Semiconductors

LX XXXX

BIN1: XX-XX-X-XXX-X

RoHS Compliant

(6P) BATCH NO: 1234567890

ML Temp ST
X XXX °C X

(1T) LOT NO: 1234567890

(9D) D/C: 1234

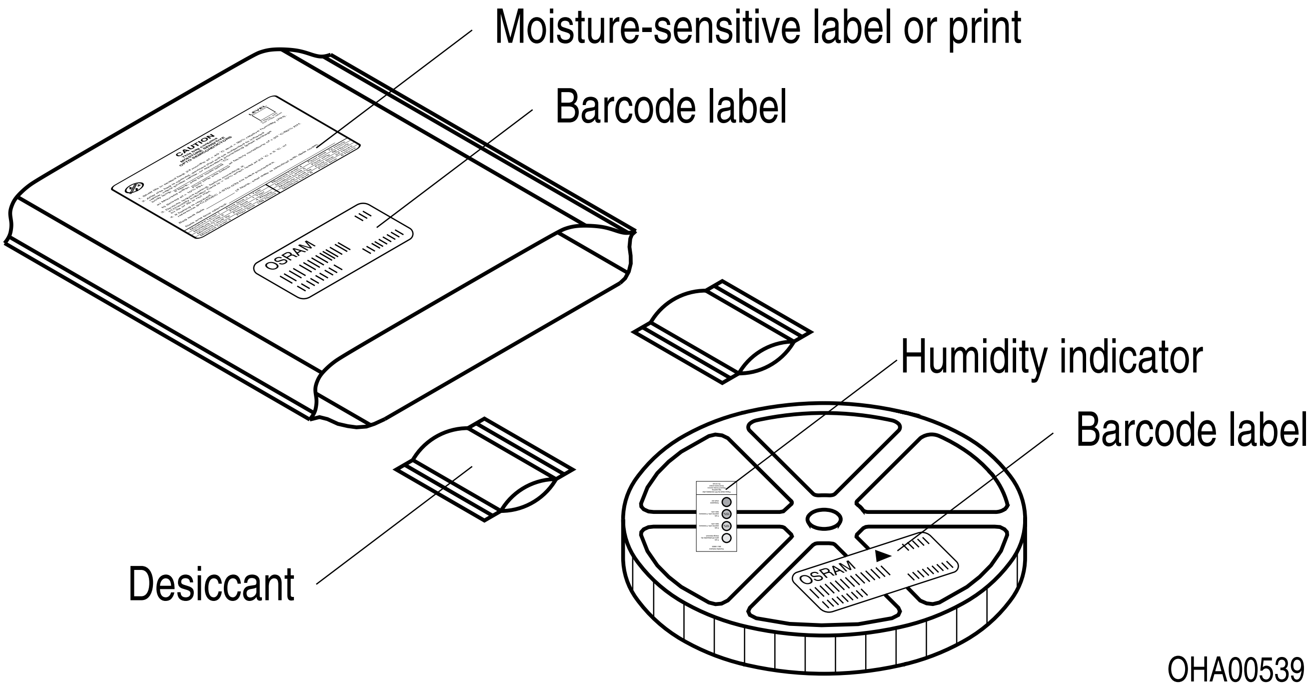
Pack: RXX

DEMY XXX

X_X123_1234.1234 X

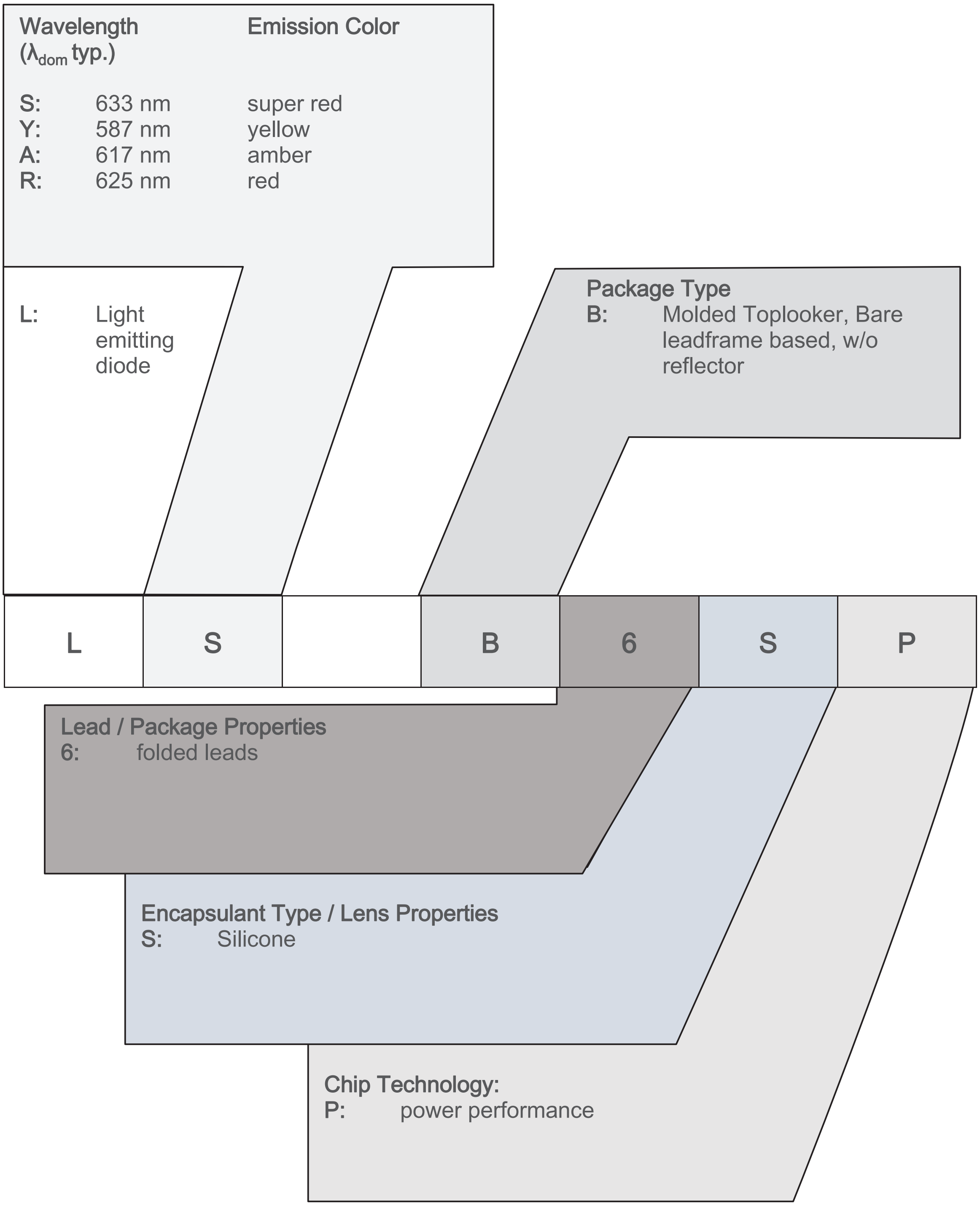
(X) PROD NO: 123456789(Q)QTY: 9999 (G) GROUP: XX-XX-X-X

Dry Packing Process and Materials 8)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Type Designation System



Wavelength (λ_{dom} typ.)		Emission Color
S:	633 nm	super red
Y:	587 nm	yellow
A:	617 nm	amber
R:	625 nm	red

L: Light emitting diode

Package Type
B: Molded Toplooker, Bare leadframe based, w/o reflector

L S B 6 S P

Lead / Package Properties
6: folded leads

Encapsulant Type / Lens Properties
S: Silicone

Chip Technology:
P: power performance

Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes

Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.
For information on the types in question please contact our Sales Organization.
If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.
OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.

Glossary

[1] **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±8 % and an expanded uncertainty of ±11 % (acc. to GUM with a coverage factor of k = 3).

[2] **Reverse Operation:** This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.

[3] **Wavelength:** The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ±0.5 nm and an expanded uncertainty of ±1 nm (acc. to GUM with a coverage factor of k = 3).

[4] **Forward Voltage:** The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ±0.05 V and an expanded uncertainty of ±0.1 V (acc. to GUM with a coverage factor of k = 3).

[5] **Thermal Resistance:** Rth max is based on statistic values (6σ).

[6] **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.

[7] **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.

[8] **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.

[9] **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

Revision History

Version	Date	Change
1.4	2019-08-29	Ordering Information Brightness Groups Disclaimer
1.5	2020-06-29	Features Schematic Transportation Box Dimensions of Transportation Box Glossary

Published by OSRAM Opto Semiconductors GmbH
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EU RoHS and China RoHS compliant product

此产品符合欧盟 RoHS 指令的要求；
按照中国的相关法规和标准，不含有毒有害物质或元素。

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ВМЕСТЕ МЫ СОЗДАЕМ БУДУЩЕЕ

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Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

http://moschip.ru/get-element

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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